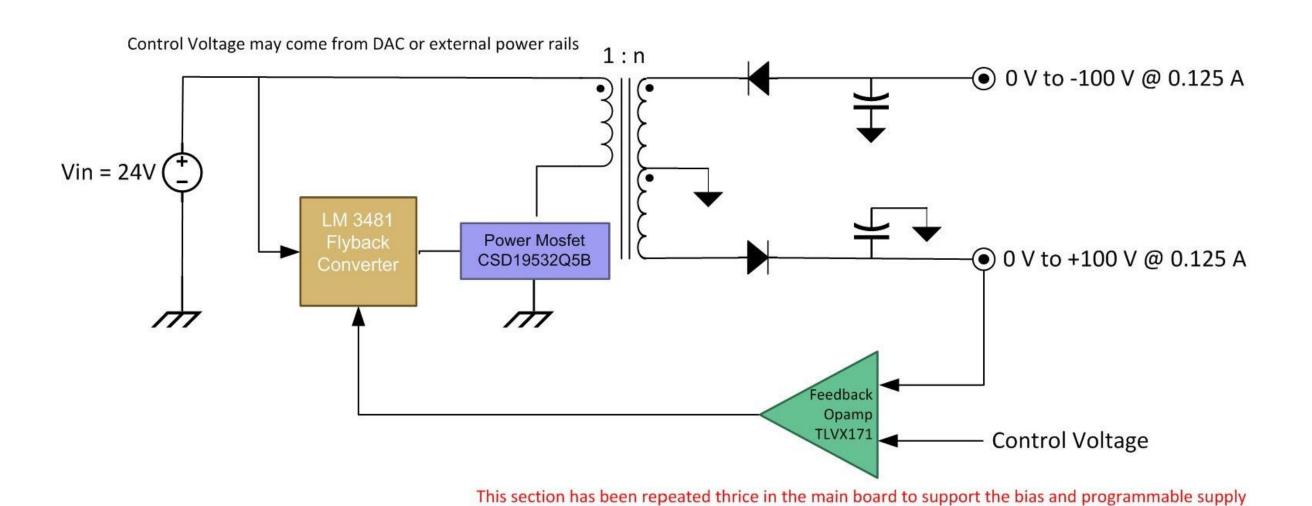
Revision History

Rev ECN # Approved Date Approved by Notes





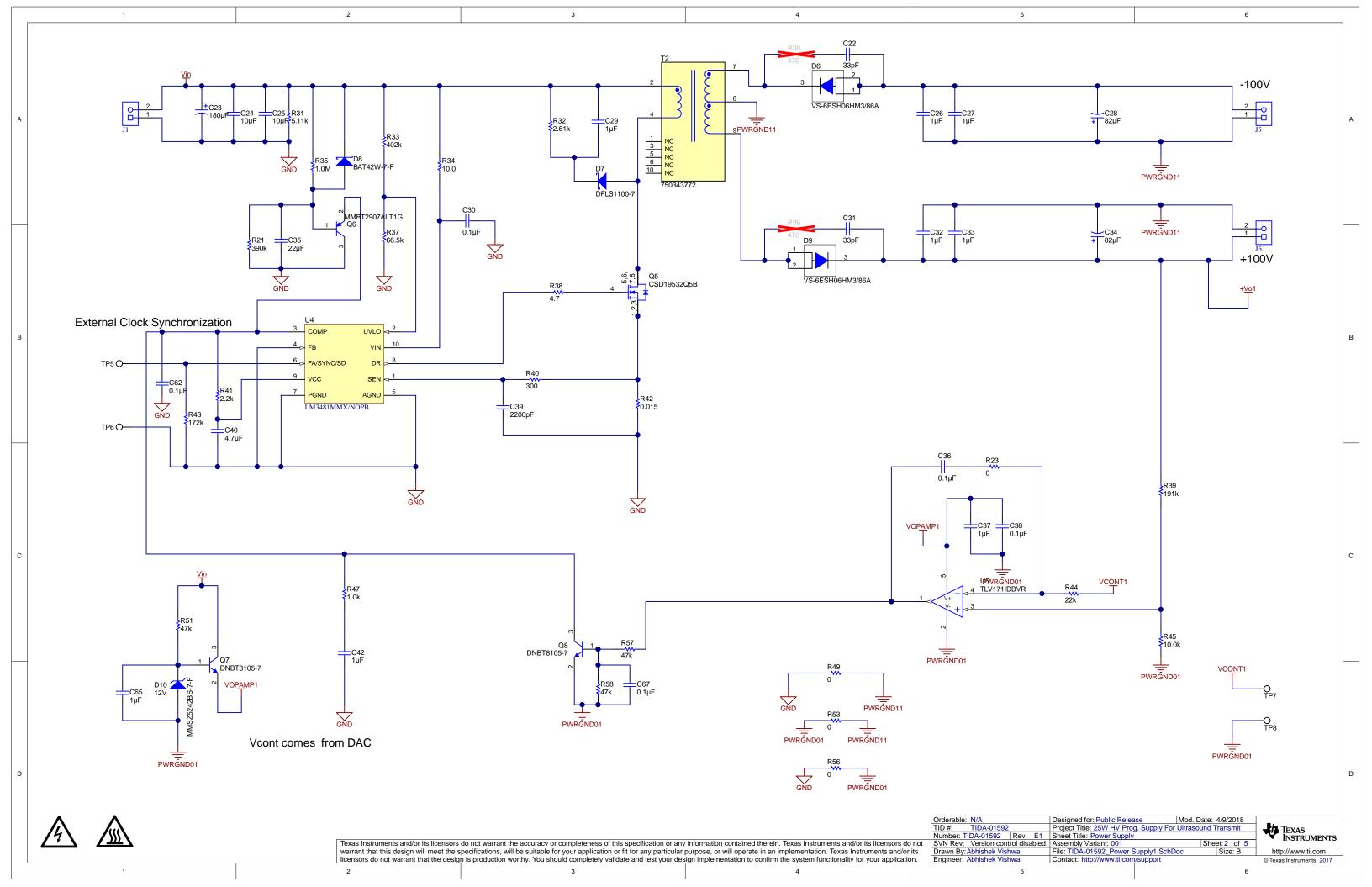
for the transmit circuit

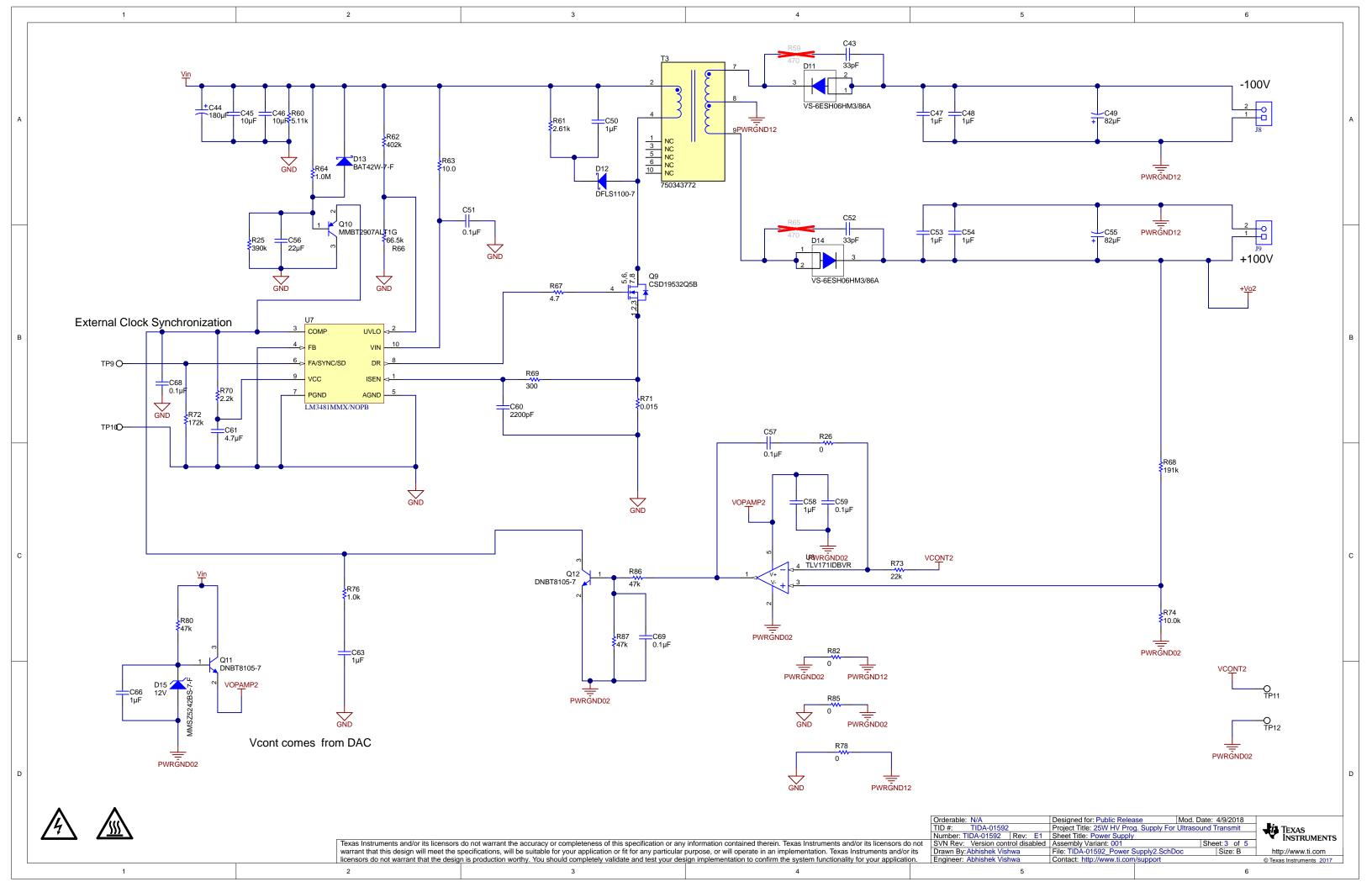
Orderable: N/A Designed for: Public Release Mod. Date: 12/19/2017
TID #: TIDA-01592 Project Title: 25W HV Prog. Supply For Ultrasound Transmit
Number: TIDA-01592 Rev: E1 Sheet Title: Block Diagram
SVN Rev: Version control disabled Assembly Variant: 001 Sheet: 1 of 5
Drawn Bw; Abhishek Vishwa File: TIDA-01592 CoverSheet SchDoc Size: R

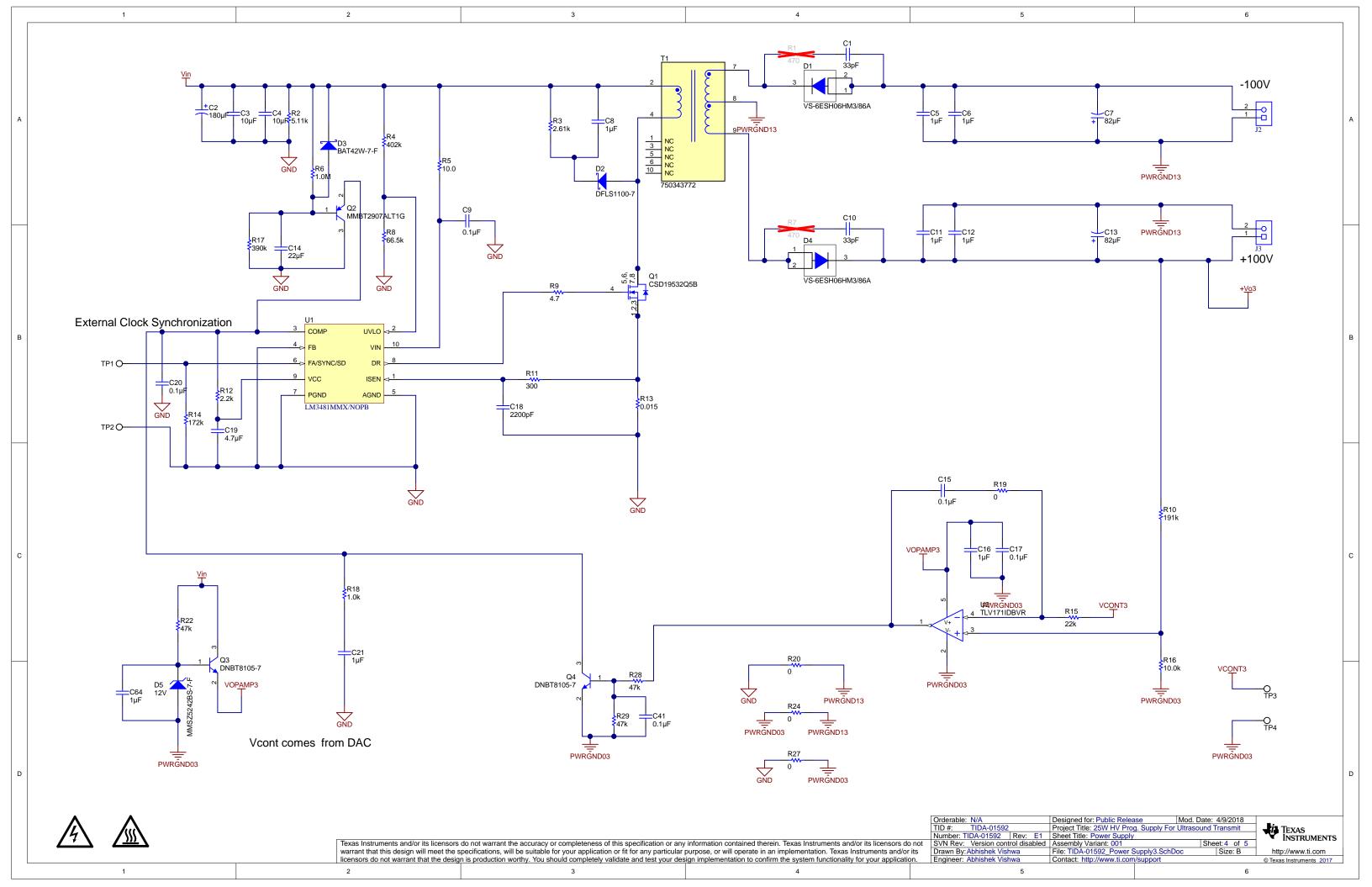
TEXAS INSTRUMENTS

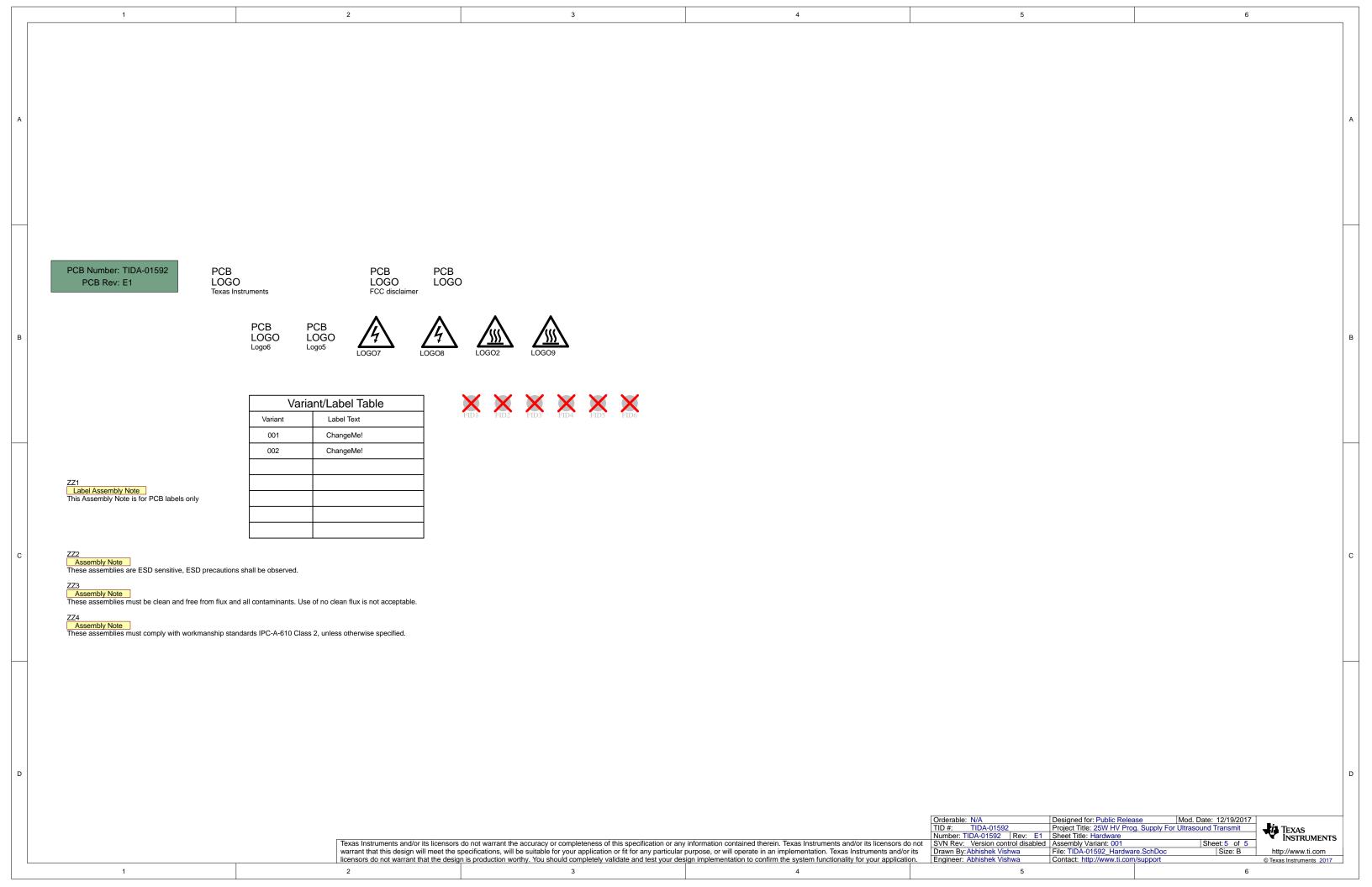
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